

WHAT IS CLAIMED IS:

1. A chip-type semiconductor light-emitting device, comprising:
 - a substrate;
 - a pair of electrodes formed on said substrate;
 - 5 a semiconductor light-emitting chip electrically connected to said pair of electrodes;
 - a mold encapsulating respective parts of said semiconductor light-emitting chip and said pair of electrodes; and
 - 10 a step formed in said electrodes at an inside of said mold and having a height increasing from an outer side to an inner side thereof.
2. A chip-type semiconductor light-emitting device according to claim 1, wherein said electrode includes a Cu layer, and said step being formed by changing a wall thickness of said Au layer.
3. A chip-type semiconductor light-emitting device according to claim 1 or 2, 15 wherein said electrode includes an Au layer formed in an uppermost layer thereof.